CLT 500X: 
Versatile and flexible laser glass processing system

The CLT 500X is a versatile laser processing system for fully strengthened glass, Corning® Gorilla® glass, un-strengthened glass, as well as other transparent glass and crystalline materials. It is specifically designed for use in an industrial environment and is often used in R&D and small scale production.

Using the Corning Laser Technologies process of ultra-short laser pulses, the CLT 500X cuts by material disassociation rather than ablation. This results in a very low surface roughness, and an increased as-cut edge strength of the glass, compared to ablative laser processes or conventional score and break methods.

For processing different types of material, the system can be equipped with multiple laser sources. This expands the scope of the system and makes it future-proof for coming applications.

The CLT 500X features a high-precision X/Y-table with dynamic linear motor drives. The table and the laser source are mounted on a machine base and vertical structure made from solid granite blocks. This ensures maximum stability even under high acceleration/deceleration. The result is a very high positioning accuracy of less than 5 µm (per 200 mm travel) and a repeatability of less than 2 µm.

Key Benefits
- nanoPerforation process to perforate the substrate
- Separation process to separate the substrate
- Free-form, net-shape or near net-shape cutting at up to 1m/s
- Cuts: curved, straight, perpendicular and angled lines as well as holes and slots
- Cuts glass from <50µm up to 6 mm in thickness

Applications
Versatile multi purpose and flexible laser machining system for:

Processing Glass Substrates
- Automotive interior glass
- Consumer electronics
- Architectural glass
- Display technologies
- Coated substrates
- Thin glass
- Strengthened and non-strengthened glass
- Drilling of through holes and vias
- Electronic components

This system is also extremely well suited for different kinds of Micro Materials Processing, such as:

Other Materials
- Cutting and drilling of OLED, PI, wafer, ceramic, plastic, and other brittle materials.
### CLT 500X Technical Specifications

#### Mechanics
- **X/Y-table machine system with highly dynamic linear motor drives**
- Machine base and vertical structure are made from solid granite blocks
- Class 1 laser safety chamber
- Pneumatically operated access door

#### Axes

<table>
<thead>
<tr>
<th>Axis</th>
<th>Travel</th>
<th>Drive</th>
</tr>
</thead>
<tbody>
<tr>
<td>X-axis</td>
<td>450 mm</td>
<td>Linear motor</td>
</tr>
<tr>
<td>Y-axis</td>
<td>660 mm</td>
<td>Linear motor</td>
</tr>
<tr>
<td>Z-axis</td>
<td>100 mm</td>
<td>Rotation motor</td>
</tr>
</tbody>
</table>

- Max. traverse speed x/y-axis: > 60 m/min
- Positioning accuracy x-axis: < 5 µm / 200 mm travel
- Positioning accuracy y-axis: < 5 µm / 200 mm travel
- Repeatability x-axis: < 2 µm
- Repeatability y-axis: < 2 µm

#### CNC-Control
- TwinCat 3 CNC control for all machine functions (G-code)

#### Operator Surface
- Based on Microsoft Windows 7 with CLT HMI

#### Loading
- Manual loading of substrates onto worktable

#### Machine Vision
- Integrated in standard configuration for fiducially recognition

#### Options
- Drop out laser process for circular inner contours
- Ablative drilling process
- Fully automated carrier return
- Full automation by use of transfer carrier

#### Electrical Supply
- **Rating**
- Power consumption (peak/average): 400 Volts, 3Ph+N+PE, 50/60 Hz (transformer available)
- 9 kVA / 6.1 kVA

#### Cooling
- **Rating (peak/average)**
- Power consumption: 3.0 kW / 2.0 kW
- Consumption: min. 8 l/min; max. 12 l/min

#### Compressed Air
- **Supply pressure**
- Consumption: min. 6 bar / max. 8 bar
- Typ. 50 l/min, peak: 100 std. liter/min at 50% duty cycle

#### Exhaust Air from Machine Enclosure
- **Volume**: min. 50 m³/h

#### Exhaust Air from Process Head
- **Volume**: up to 150 m³/h exhaust air

#### Machine Vacuum
- No requirement at customer site
- Will be generated inside the equipment

#### Machine Size and Weight
- **Size**: Width x Depth x Height: 1650 x 2100 x 2300 mm (excluding service area)
- **Weight**: approx. 3,800 kg

#### Temperature
- 18 °C min., 22 °C max., non condensing
- Deviation +/- 2 °C

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1) Nominal travel range. Effective travel range may be reduced by use of multiple process heads and/or cameras.
2) Environmental controlled room required.
3) These values may vary, depending on the tool configuration, e.g. type of laser source. Specifications are subject to change without notice.

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